AMENDMENTS TO THE CLAIMS:

This listing of claims replaces all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A method ~~for~~ of producing ~~submerged bondable terminal pads (AF) in~~ a component ~~containing~~ comprised of at least ~~two joined~~ first and second substrates ~~(S1, S2)~~, the first substrate having an upper surface that contains terminal pads, and the [[-]] ~~wherein there is a~~ first substrate ~~(S1) including~~ comprising ~~electrically conductive~~ component structures that are electrically conductive and that[[,]] ~~where the component structures~~ are electrically connected to the ~~forenamed~~ terminal pads ~~(AF), which are located on a surface of the first substrate (S1)~~, the second substrate having a lower surface that faces the upper surface of the first substrate, the method comprising:

[[-]] ~~wherein~~ forming grooves ~~(G) with~~ having a ~~specified~~ predefined depth on the lower surface of the second substrate;[[,]] ~~which delimit at least one cutout (AS) are produced in a surface of a second substrate (S2),~~ [[-]] ~~wherein the first and the second substrate are joined together in such a way that the surfaces of the two substrates that are provided with the terminal pads and the grooves face each other~~[[,]]

[[-]] ~~wherein~~ forming incisions ~~(ES) are produced~~ on an upper surface of the second substrate, the incisions reaching the grooves to form a cutout portion in the second substrate; and ~~over the grooves from the back of the second substrate, which is now on the outside, to a depth such that the grooves (G) are opened there,~~

[[-]] ~~wherein at least one~~ removing the cutout portion to expose the terminal pads ~~(AS) is removed, so that the contact pads (AF) are exposed~~.

2. (Currently Amended) The method ~~as recited in~~ of claim 1, wherein the grooves ~~(G)~~ and the incisions ~~(ES) following the grooves~~ are ~~produced~~ formed in substantially straight lines ~~running over the entire~~ on the second substrate; ~~(S2),~~

wherein the incisions are produced by sawing[[,]]; and

wherein ~~a~~ the cutout portion ~~(AS) for exposing the terminal pads (AF)~~ is defined between ~~each~~ a pair of grooves.

3. (Currently Amended) The method ~~as recited in~~ of claim 2, wherein ~~each case a plurality of~~ the terminal pads ~~(AF) of the first substrate (S1)~~ are positioned side by side in a row on the upper surface of the first substrate; [[,]] and

wherein ~~each of the cutouts (AS)~~ the cutout portion exposes ~~one of the rows~~ the row of terminal pads ~~(AF)~~.

4. (Currently Amended) The method of claim 1 ~~as recited in one of claims 1 through 3~~, wherein the grooves ~~(G) are produced by~~ are formed via wet chemical etching, ion beam etching, or plasma etching.

5. (Currently Amended) The method ~~as recited in~~ of claim 4, wherein the grooves ~~(G)~~ are defined by ~~means of~~ a resistance mask ~~which~~ that is structured

photolithographically.

6. (Currently Amended) The method of claim 1 ~~as recited in one of claims 1 through 3~~, wherein the grooves ~~(G)~~ are ~~produced~~ formed by laser cutting.

7. (Currently Amended) The method of claim 2 ~~as recited in one of claims 1 through 6~~, wherein the grooves ~~(G)~~ are ~~produced~~ formed to a depth ~~which~~ that is greater than ~~the~~ a cutting depth precision of ~~the~~ a sawing process ~~procedure when producing~~ used to form the incisions ~~(ES).~~

8. (Currently Amended) The method of claim 1, further comprising:

joining the substrates; and

~~as recited in one of claims 1 through 7,~~ shaping at least one of the first and second substrates to produce a ~~wherein before the surfaces of the two substrates (S1, S2) are joined at least one of the surfaces is shaped so that after they are joined a free~~ clearance ~~is produced over~~ between the terminal pads and ~~(AF) at a distance from the corresponding surfaces of~~ the second substrate ~~(S2)~~.

9. (Currently Amended) The method of claim 8, further comprising: ~~as recited in one of claims 1 through 7, wherein before the surfaces are joined~~

before joining the first and second substrates, applying a covering ~~is produced on the first substrate (S1)~~ over at least ~~over~~ the terminal pads to prevent the second substrate

from adhering to the terminal pads; and ~~(AF) or under the later cutout (AS) of the second substrate (S2), so that when they are joined direct adhesion of the second substrate to the terminal pads is prevented, and wherein~~

removing the covering after removing the cutout portion ~~is removed again after the cutout is produced~~.

10. (Currently Amended) The method of claim 8 ~~as recited in one of claims 1 through 9~~, wherein ~~the procedure for joining the substrates (S1, S2) includes one of the following measures:~~ the first and second substrates are joined via glass bonding, bonding by means of bumps, anodic bonding, eutectic bonding, direct bonding of substrate surfaces ~~consisting of semiconductor material~~, or gluing.

11. (Currently Amended) The method of claim 1 ~~as recited in one of claims 1 through 10~~, wherein the first and second substrates comprise wafers; and

wherein the method further comprises separating individual components from the first and second substrates after the cutout portion is removed ~~wafers are employed as substrates (S1, S2), with a plurality of components being formed at least in the first substrate, which are separated after the terminal pads (AF) are exposed~~.

12. (Currently Amended) The method ~~as recited in~~ of claim 11, wherein ~~the~~ terminal pads ~~(AF) of each component~~ of individual components are ~~arranged in rows which are directly adjacent to~~ on edges of the individual components; ~~component, with the~~

~~rows of directly adjacent components running beside each other,~~ and

wherein ~~each cutout (AS) the~~ removal of the cutout portion exposes two adjacent rows of terminal pads for ~~of~~ adjacent components ~~are exposed~~.

13. (Currently Amended) The method of claim 1 ~~as recited in one of claims 1 through 12~~, wherein at least one of the first and second substrates ~~(S1, S2)~~ comprises microelectrical components, micro-optical components, ~~or~~ micro-mechanical components or a combination thereof ~~combined components of the forenamed types are realized~~.

14. (New) A method of producing a component comprised of first and second substrates that are joined via an upper surface of the first substrate and a lower surface of the second substrate, the upper surface of the first substrate containing terminal pads, and the first substrate comprising component structures that are electrically conductive and that are electrically connected to the terminal pads, the method comprising:

forming grooves having a predefined depth on the lower surface of the second substrate, the grooves being formed in substantially straight lines via a first formation technique, a pair of the grooves defining a strip-shaped cutout portion of the second substrate;

joining the upper surface of the first substrate and the lower surface of the second substrate;

forming incisions on an upper surface of the second substrate via a second formation technique, the incisions reaching the grooves to separate the cutout portion from

a remainder of the second substrate, the first formation technique differing from the second formation technique, and the first formation technique having greater precision than the second formation technique; and

removing the cutout portion to expose the terminal pads.

15. (New) The method of claim 14, wherein the grooves are formed via wet chemical etching, ion beam etching, or plasma etching.

16. (New) The method of claim 14, wherein the grooves are defined by a resistance mask that is structured photolithographically.

17. (New) The method of claim 14, wherein the grooves are formed by laser cutting.

18. (New) The method of claim 14, further comprising:

shaping at least one of the first and second substrates to produce a clearance between the terminal pads and the second substrate.

19. (New) The method of claim 14, further comprising:

before joining the first and second substrates, applying a covering over at least the terminal pads to prevent the second substrate from adhering to the terminal pads; and

removing the covering after removing the cutout portion.

20. (New) The method of claim 14, wherein the first and second substrates are joined via glass bonding, bonding by means of bumps, anodic bonding, eutectic bonding, direct bonding of substrate surfaces, or gluing.